SPECIFICATIONS FOR NICHIA WHITE LED

$\mathsf{MODEL}:NSPWF50BS$

NICHIA CORPORATION

(Ta=25°C)

1.SPECIFICATIONS

(1) Absolute Maximum Ratings			(Ta=25°C)
Item	Symbol	Absolute Maximum Rating	Unit
Forward Current	IF	30	mA
Pulse Forward Current	IFP	100	mA
Reverse Voltage	VR	5	V
Power Dissipation	Pd	120	mW
Operating Temperature	Topr	$-30 \sim + 85$	°C
Storage Temperature	Tstg	$-40 \sim +100$	°C
Soldering Temperature	Tsld	265°C for 10sec.	

IFP Conditions : Pulse Width ≤ 10 msec. and Duty $\leq 1/10$

(2) Initial Electrical/Optical Characteristics

1								/
	Item		Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Vo	ltage		VF	IF=20[mA]	-	3.6	4.0	V
Reverse Cu	rrent		Ir	$V_{R}=5[V]$	-	-	50	μA
		Rank S	Iv	IF=20[mA]	340	410	480	mcd
Luminous I	ntensity	Rank R	Iv	IF=20[mA]	240	300	340	mcd
		Rank Q	Iv	IF=20[mA]	170	205	240	mcd

* Measurement Uncertainty of the Luminous Intensity : $\pm 10\%$

Color Ranks

	Rank a0				
Х	0.280	0.264	0.283	0.296	
у	0.248	0.267	0.305	0.276	
	Rank b2				
Х	0.296	0.287	0.330	0.330	
v	0.276	0.295	0.339	0.318	

(IF=20mA,Ta=25°C)							
		Rank b1					
Х	0.287	0.283	0.330	0.330			
у	0.295	0.305	0.360	0.339			
	Rank c0						
х	0.330	0.330	0.361	0.356			
у	0.318	0.360	0.385	0.351			

* Measurement Uncertainty of the Color Coordinates : ± 0.01

* One delivery will include up to two consecutive color ranks and three luminous intensity ranks of the products. The quantity-ratio of the ranks is decided by Nichia.

2.TYPICAL INITIAL OPTICAL/ELECTRICAL CHARACTERISTICS Please refer to figure's page.

3.OUTLINE DIMENSIONS AND MATERIALS

Please refer to figure's page.

Material as follows;	Resin(Mold) :	Epoxy Resin (over YAG Phosphor)
	Leadframe :	Ag plating Copper Alloy

4.PACKAGING

• The LEDs are packed in cardboard boxes after packaging in anti-electrostatic bags. According to the total delivery amount, cardboard boxes will be used to protect the LEDs from mechanical shocks during transportation. Please refer to figure's page. The label on the minimum packing unit bag shows; Part Number, Lot Number, Ranking, Quantity

· The boxes are not water resistant and therefore must be kept away from water and moisture.

5.LOT NUMBER

The first six digits number shows lot number.

The lot number is composed of the following characters;

 \bigcirc \bigcirc \times \times \times \land \land

- \bigcirc Year (1 for 2001, 2 for 2002)
- \Box Month (1 for Jan., 9 for Sep., A for Oct., B for Nov.)
- $\times \times \times \times$ Nichia's Product Number
 - \triangle Ranking by Color Coordinates
 - Ranking by Luminous Intensity

6.RELIABILITY (1) TEST ITEMS AND RESULTS

	Standard			Number of
Test Item	Test Method	Test Conditions	Note	Damaged
Resistance to	JEITA ED-4701	Tsld= $260 \pm 5^{\circ}$ C, 10sec.	1 time	0/100
Soldering Heat	300 302	3mm from the base of the epoxy bulb		
Solderability	JEITA ED-4701	Tsld= $235 \pm 5^{\circ}$ C, 5sec.	1 time	0/100
	300 303	(using flux)	over 95%	
Thermal Shock	JEITA ED-4701	$0^{\circ}C \sim 100^{\circ}C$	100 cycles	0/100
	300 307	15sec. 15sec.		
Temperature Cycle	JEITA ED-4701	$-40^{\circ}\mathrm{C} \sim 25^{\circ}\mathrm{C} \sim 100^{\circ}\mathrm{C} \sim 25^{\circ}\mathrm{C}$	100 cycles	0/100
	100 105	30min. 5min. 30min. 5min.		
Moisture Resistance Cyclic	JEITA ED-4701	$25^{\circ}\text{C} \sim 65^{\circ}\text{C} \sim -10^{\circ}\text{C}$	10 cycles	0/100
	200 203	90%RH 24hrs./1cycle		
Terminal Strength	JEITA ED-4701	Load 5N (0.5kgf)	Nonoticeable	0/100
(bending test)	400 401	$0^{\circ} \sim 90^{\circ} \sim 0^{\circ}$ bend 2 times	damage	
Terminal Strength	JEITA ED-4701	Load 10N (1kgf)	Nonoticeable	0/100
(pull test)	400 401	10 ± 1 sec.	damage	
High Temperature Storage	JEITA ED-4701	Ta=100°C	1000hrs.	0/100
	200 201			
Temperature Humidity	JEITA ED-4701	Ta=60°C, RH=90%	1000hrs.	0/100
Storage	100 103			
Low Temperature Storage	JEITA ED-4701	Ta=-40°C	1000hrs.	0/100
	200 202			
Steady State Operating Life		Ta=25°C, IF=30mA	1000hrs.	0/100
Steady State Operating Life		60°C, RH=90%, IF=20mA	500hrs.	0/100
of High Humidity Heat				
Steady State Operating Life		Ta=-30°C, IF=20mA	1000hrs.	0/100
of Low Temperature				

(2) CRITERIA FOR JUDGING THE DAMAGE

			Criteria for Judgement		
Item	Symbol	Test Conditions	Min.	Max.	
Forward Voltage	VF	IF=20mA	-	U.S.L.*)× 1.1	
Reverse Current	Ir	Vr=5V	-	U.S.L.*) \times 2.0	
Luminous Intensity	Iv	IF=20mA	L.S.L.**) \times 0.7	-	

*) U.S.L. : Upper Standard Level **) L.S.L. : Lower Standard Level

7.CAUTIONS

White LEDs are devices which are materialized by combining Blue LEDs and special phosphors. Consequently, the color of White LEDs is changed a little by an operating current. Care should be taken after due consideration when using LEDs.

(1) Lead Forming

 \cdot When forming leads, the leads should be bent at a point at least 3mm from the base of the epoxy bulb. Do not use the base of the leadframe as a fulcrum during lead forming.

- · Lead forming should be done before soldering.
- \cdot Do not apply any bending stress to the base of the lead. The stress to the base may damage the characteristics or it may break the LEDs.
- When mounting the LEDs onto a printed circuit board, the holes on the circuit board should be exactly aligned with the leads of the LEDs. If the LEDs are mounted with stress at the leads, it causes deterioration of the epoxy resin and this will degrade the LEDs.
- (2) Storage
 - The LEDs should be stored at 30°C or less and 70%RH or less after being shipped from Nichia and the storage life limits are 3 months. If the LEDs are stored for 3 months or more, they can be stored for a year in a sealed container with a nitrogen atmosphere and moisture absorbent material.
- Nichia LED leadframes are comprised of a silver plated copper alloy. The silver surface may be affected by environments which contain corrosive gases and so on. Please avoid conditions which may cause the LED to corrode, tarnish or discolor. This corrosion or discoloration may cause difficulty during soldering operations. It is recommended that the LEDs be used as soon as possible.
- Please avoid rapid transitions in ambient temperature, especially, in high humidity environments where condensation can occur.

(3) Static Electricity

· Static electricity or surge voltage damages the LEDs.

It is recommended that a wrist band or an anti-electrostatic glove be used when handling the LEDs.

- All devices, equipment and machinery must be properly grounded. It is recommended that measures be taken against surge voltage to the equipment that mounts the LEDs.
- When inspecting the final products in which LEDs were assembled, it is recommended to check whether the assembled LEDs are damaged by static electricity or not. It is easy to find static-damaged LEDs by a light-on test or a VF test at a lower current (below 1mA is recommended).
- Damaged LEDs will show some unusual characteristics such as the leak current remarkably increases, the forward voltage becomes lower, or the LEDs do not light at the low current.

Criteria : (VF > 2.0V at IF=0.5mA)

(4) Soldering Conditions

- Nichia LED leadframes are comprised of a silver plated copper alloy. This substance has a low thermal coefficient (easily conducts heat). Careful attention should be paid during soldering.
- Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.
- \cdot Recommended soldering conditions

Dip Soldering		Soldering		
Pre-Heat	100°C Max.	Temperature	300°C Max.	
Pre-Heat Time	60 seconds Max.	Soldering Time	3 seconds Max.	
Solder Bath	260°C Max.	Position	No closer than 3 mm from the	
Temperature			base of the epoxy bulb.	
Dipping Time	10 seconds Max.			
Dipping Position	No lower than 3 mm from the			
	base of the epoxy bulb.			

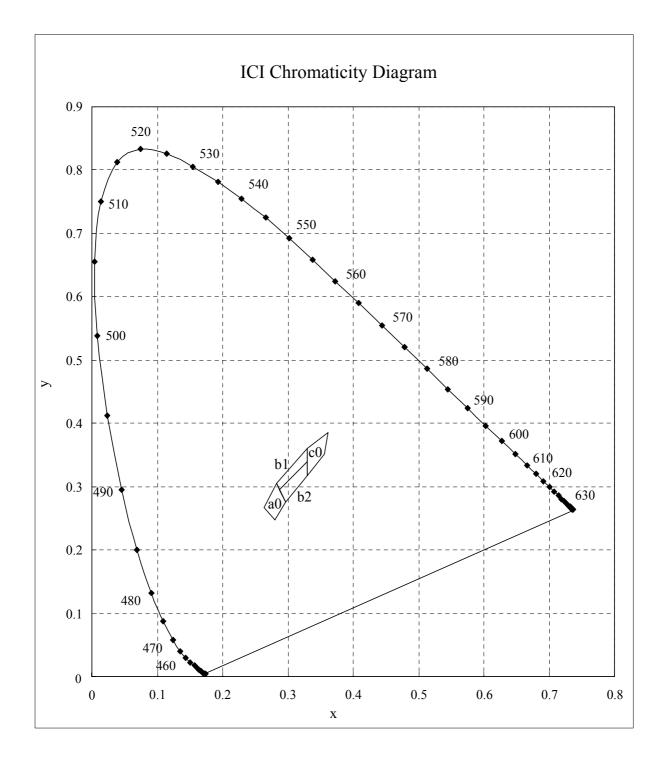
- \cdot Do not apply any stress to the lead particularly when heated.
- \cdot The LEDs must not be repositioned after soldering.
- \cdot After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused from warping of the PC board or from the clinching and cutting of the leadframes. When it is absolutely necessary, the LEDs may be mounted in this fashion but the User will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. Nichia's LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.
- \cdot When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- \cdot Cut the LED leadframes at room temperature. Cutting the leadframes at high temperatures may cause failure of the LEDs.
- (5) Heat Generation
 - Thermal design of the end product is of paramount importance. Please consider the heat generation of the LED when making the system design. The coefficient of temperature increase per input electric power is affected by the thermal resistance of the circuit board and density of LED placement on the board, as well as other components. It is necessary to avoid intense heat generation and operate within the maximum ratings given in this specification.
 - \cdot The operating current should be decided after considering the ambient maximum temperature of LEDs.
- (6) Cleaning
 - It is recommended that isopropyl alcohol be used as a solvent for cleaning the LEDs. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the resin or not. Freon solvents should not be used to clean the LEDs because of worldwide regulations.
 - Do not clean the LEDs by the ultrasonic. When it is absolutely necessary, the influence of ultrasonic cleaning on the LEDs depends on factors such as ultrasonic power and the assembled condition. Before cleaning, a pre-test should be done to confirm whether any damage to the LEDs will occur.

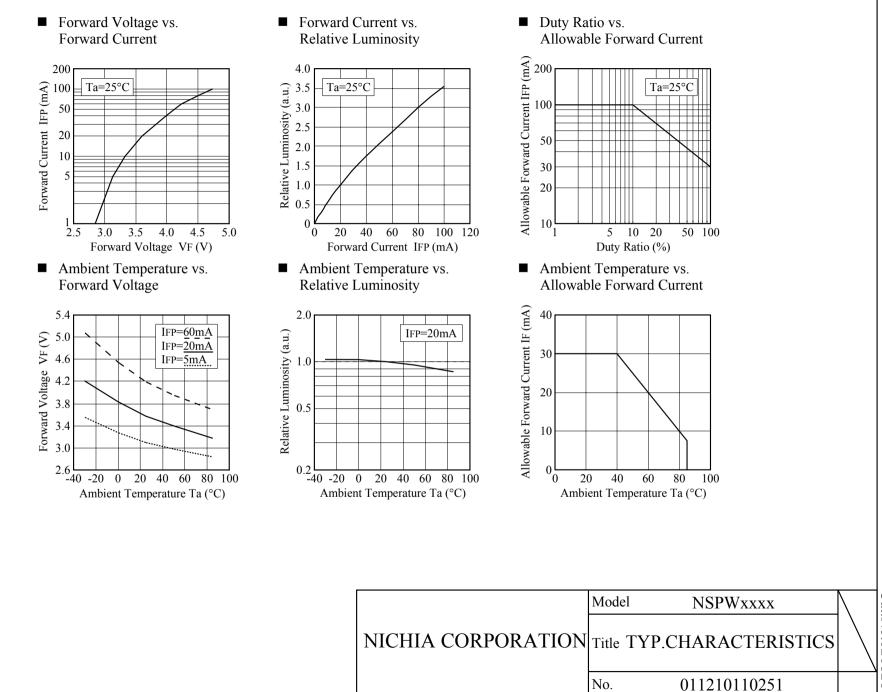
(7) Safety Guideline for Human Eyes

In 1993, the International Electric Committee (IEC) issued a standard concerning laser product safety (IEC 825-1). Since then, this standard has been applied for diffused light sources (LEDs) as well as lasers. In 1998 IEC 60825-1 Edition 1.1 evaluated the magnitude of the light source.
In 2001 IEC 60825-1 Amendment 2 converted the laser class into 7 classes for end products. Components are excluded from this system. Products which contain visible LEDs are now classified as class 1. Products containing UV LEDs are class 1M. Products containing LEDs can be classified as class 2 in cases where viewing angles are narrow, optical manipulation intensifies the light, and/or the energy emitted is high. For these systems it is recommended to avoid long term exposure. It is also recommended to follow the IEC regulations regarding safety and labeling of products.

(8) Others

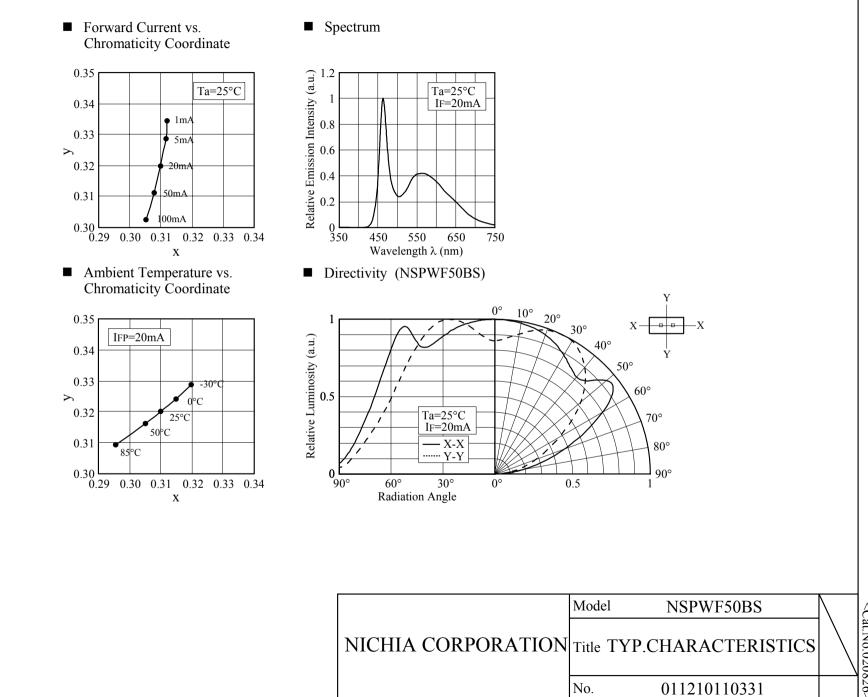
- \cdot Care must be taken to ensure that the reverse voltage will not exceed the absolute maximum rating when using the LEDs with matrix drive.
- The LEDs described in this brochure are intended to be used for ordinary electronic equipment (such as office equipment, communications equipment, measurement instruments and household appliances). Consult Nichia's sales staff in advance for information on the applications in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health (such as for airplanes, aerospace, submersible repeaters, nuclear reactor control systems, automobiles, traffic control equipment, life support systems and safety devices).
- User shall not reverse engineer by disassembling or analysis of the LEDs without having prior written consent from Nichia. When defective LEDs are found, the User shall inform Nichia directly before disassembling or analysis.
- \cdot The formal specifications must be exchanged and signed by both parties before large volume purchase begins.
- · The appearance and specifications of the product may be modified for improvement without notice.

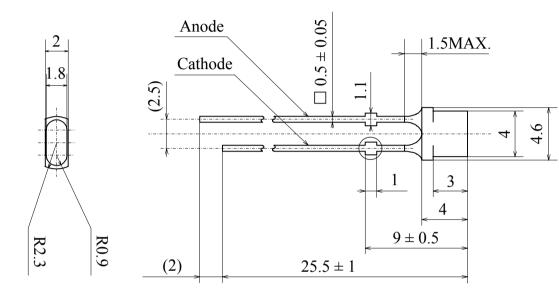




÷

Nichia STSE-CW2167A <Cat.No.020826>





ITEM	MATERIALS			
RESIN	Epoxy Resin (over YAG Phosphor)			
LEAD FRAME	Ag Plating Copper Alloy			

Remark:

Bare copper alloy is exposed at tie-bar portion after cutting.

The lamps have sharp and hard points that may injure human eyes or fingers etc., so please pay enough care in the handling.

1		N	-
Model	NSPWF50BS	$\sum_{i=1}^{n}$	A.
Title	OUTLINE DIMENSIONS	3/1 Scale	at.No.020
No.	010817105011	$\begin{array}{c} Allow \\ \pm \ 0.2 \end{array}$)826>
	Title	Title OUTLINE DIMENSIONS	Title OUTLINE DIMENSIONS 3/1 Scale

